

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Doo Sung LEE</td> <td>02/05/2013</td> </tr> <tr> <td>Bong Sup KIM</td> <td>02/05/2013</td> </tr> <tr> <td>Cong Truc HUYNH</td> <td>02/05/2013</td> </tr> </tbody> </table>		Name	Execution Date	Doo Sung LEE	02/05/2013	Bong Sup KIM	02/05/2013	Cong Truc HUYNH	02/05/2013
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Doo Sung LEE	02/05/2013								
Bong Sup KIM	02/05/2013								
Cong Truc HUYNH	02/05/2013								
RECEIVING PARTY DATA									
Name:	RESEARCH & BUSINESS FOUNDATION SUNGKYUNKWAN UNIVERSITY								
Street Address:	c/o Sungkyunkwan University, 300 Cheoncheon-dong, Jangan-gu, Suwon-si, Gyeonggi-do 440-746								
City:	Suwon-si								
State/Country:	KOREA, REPUBLIC OF								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13761419</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13761419				
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Application Number:	13761419								
CORRESPONDENCE DATA									
Fax Number:	2023153758								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	202-429-0020								
Email:	info@nsiplaw.com								
Correspondent Name:	NSIP LAW								
Address Line 1:	P.O. Box 65745								
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20035								
ATTORNEY DOCKET NUMBER:	042099.0004								
NAME OF SUBMITTER:	Charles Y. Park								
Total Attachments: 2 source=NewApp_0420990004_DecAssignExecuted2#page1.tif source=NewApp_0420990004_DecAssignExecuted2#page2.tif									

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COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto, or to United States Application Number or PCT International Application Number _____ filed on _____ (if applicable), entitled:

pH-SENSITIVE POLYMER HYDROGEL WITH DUAL IONIC TRANSITION AND USE THEREOF

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

RESEARCH & BUSINESS FOUNDATION SUNGKYUNKWAN UNIVERSITY

c/o Sungkyunkwan University, 300 Cheoncheon-dong, Jangan-gu
Suwon-si, Gyeonggi-do 440-746
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 13/761,419 filed on February 7, 2013.

I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	Doo Sung LEE		
Inventor's Signature	<i>Doo Sung Lee</i>	Date	<i>Feb. 5, 2013</i>
Residence (City, Country)	Gwacheon-si, Republic of Korea		
Mailing Address	503-906, Jugong Apt., Byeoryang-dong, Gwacheon-si, Gyeonggi-do 427-732, Republic of Korea		

Inventor's Legal Name	Bong Sup KIM		
Inventor's Signature	<i>Bong Sup Kim</i>	Date	<i>Feb. 5, 2013</i>
Residence (City, Country)	Suwon-si, Republic of Korea		
Mailing Address	1 Floor 497-16, Seryu 3-dong, Gwonseon-gu, Suwon-si, Gyeonggi-do 441-870, Republic of Korea		

Inventor's Legal Name	Cong Truc HUYNH		
Inventor's Signature	<i>Cong Truc HUYNH</i>	Date	<i>Feb. 5, 2013</i>
Residence (City, Country)	Suwon-si, Republic of Korea		
Mailing Address	#25506, Sungkyunkwan Univ. Engineering Building, Cheoncheon-dong, Jangan-gu, Suwon-si, Gyeonggi-do 440-746, Republic of Korea		